

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
ON APPEAL FROM THE EXAMINER TO THE BOARD
OF PATENT APPEALS AND INTERFERENCES**

In re Application of: Mark T. McCormack et al.
Serial No.: 09/866,092
Filing Date: May 23, 2001
Group Art No.: 2815
Confirmation No.: 5484
Examiner: Eugene Lee
Title: *Structure and Method for Embedding Components
In Multi-Layer Substrates*

Mail Stop Appeal Brief - Patents
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

REQUEST FOR STATUS

The above-identified patent application is currently on appeal before the Board of Patent Appeals and Interferences. Applicants received an Answer in response to the Appeal Brief filed on February 15, 2008. Applicants filed a Reply Brief on August 14, 2008. Since mailing the Reply Brief to the Board, Applicants have not heard anything further regarding this application. Accordingly, Applicants respectfully request status of the present application, and in particular request notice of the approximate date on which the Board expects to issue a decision in this appeal.

If there are any matters that can be cleared up through a telephone conversation, please contact the undersigned attorney for Applicants, Brian W. Oaks, at 214.953.6986.

Respectfully submitted,
BAKER BOTTS L.L.P.
Attorneys for Applicants



Brian W. Oaks
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Dated: March 13, 2009

Customer No. **05073**